What is claimed is:

1. A method of reducing delamination in an assembly, comprising

providing an assembly, the assembly comprising

an electronic device;

a substrate having a first surface and a second surface opposite the first surface, wherein the second surface of the substrate is disposed on the electronic device;

a barrier stack disposed on the first surface of the substrate; and

a weatherable sheet adjacent the barrier film opposite the substrate;

wherein the assembly is transmissive to visible and infrared light, and

limiting visible light exposure to parts of the assembly to maintain a peel force of 20 grams/inch or greater where the light is limited.

2. The ~~assembly~~ method of claim 1 wherein the barrier stack comprises a polymer layer and an inorganic barrier layer.

3. The ~~assembly~~ method of claim 2 wherein the inorganic barrier layer is an oxide layer.

4. The ~~assembly~~ method of claim 1 wherein the ~~multilayer film~~barrier stack is transparent and flexible.

5. The ~~assembly~~ method of claim 1 wherein the electronic device comprises an encapsulant layer.

6. The ~~assembly~~ method of claim 1 wherein the electronic device comprises an edge seal material.

7. The ~~assembly~~ method of claim 1 wherein the electronic device comprises a backsheet.

8. The ~~assembly~~ method of claim 1 wherein the electronic device comprises a roof.

9. The method of claim 1 comprising a pressure sensitive adhesive layer between the weatherable sheet and the barrier stack.

10. The method of claim 1 wherein the visible light is limited by blocking light in a perimeter around the assembly.

11. The method of claim 1 wherein the visible light is limited by blocking the light near the edges of the assembly.

12. The method of claim 1 wherein the the barrier stack has a water vapor transmission rate of less than 0.005 cc/m^2/day at 50°C and 100% relative humidity.

13. The method of claim 1 wherein the barrier stack has an oxygen transmission rate of less than 0.005 cc/m^2/day at 23°C and 90% relative humidity.

14. The method of claim 1 wherein the assembly is flexible.

15. The method of claim 1 wherein the assembly is placed outside.

16. The method of claim 1 wherein the electronic device is a photovoltaic device.

17. The method of claim 1 wherein the assembly has a surface, and light exposure is limited to less than 5% of the surface area of the assembly.

18. The method of claim 17 wherein the light exposure is limited to less than 1% of the surface area of the assembly.

19. The method of claim 17 wherein the light exposure is limited to less than 0.5% of the surface area of the assembly.

20. The method of claim 1 further comprising limiting moisture exposure to ~~the~~ an interface between the barrier ~~assembly~~ stack and the substrate.

21. The method of claim 1 wherein the assembly has a maximum of 20% transmission at any wavelength between 380 and 450nm where the light has been limited.

22. The method of claim 1 wherein the assembly has a maximum of 2% transmission at any wavelength between 380 and 450nm where the light has been limited.

23. The method of claim 1 wherein the assembly has a maximum of 0.2% transmission at any wavelength between 380 and 450nm where the light has been limited.

24. The method of claim 1 wherein the visible light is limited by blocking light within 5 mm of the edge of the assembly where the light has been limited.